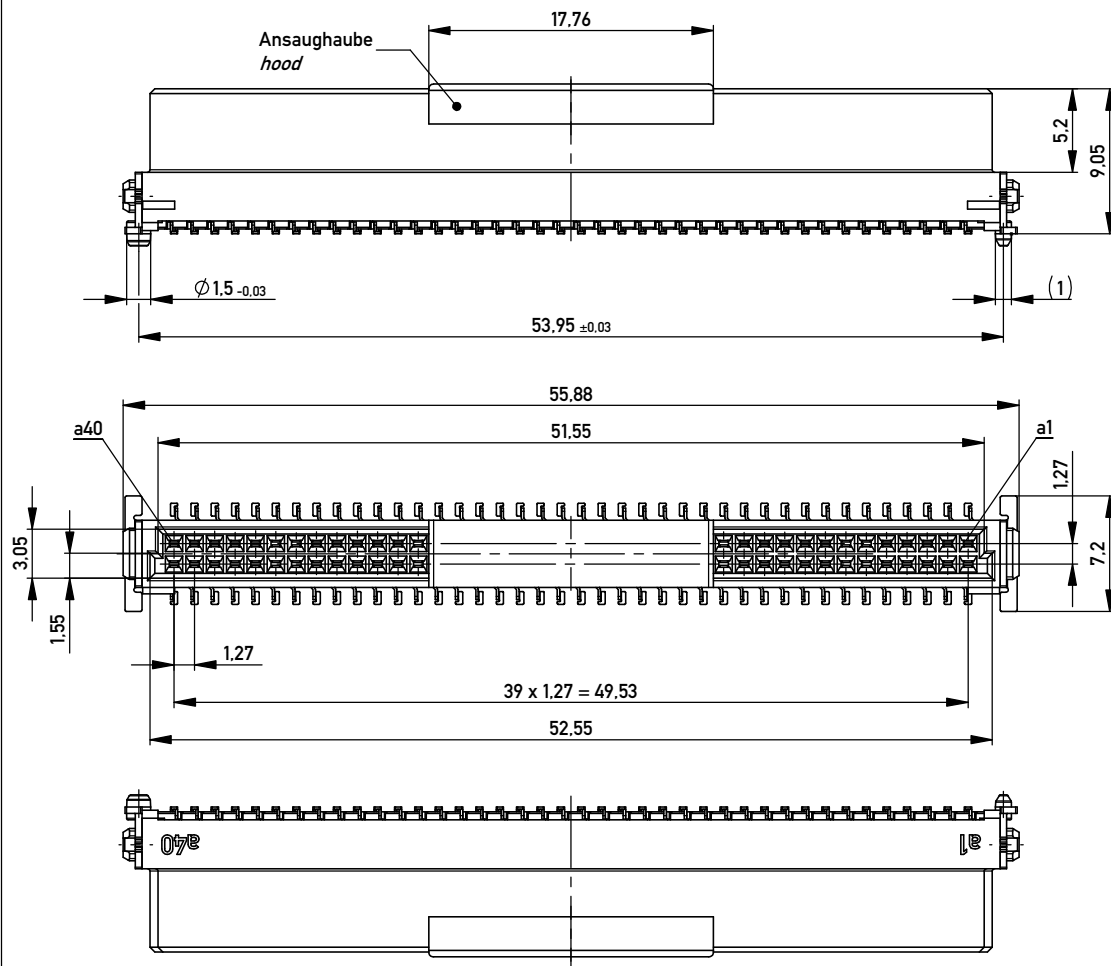
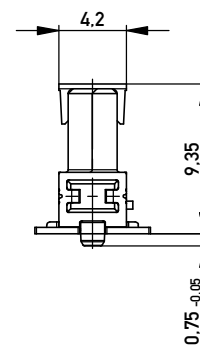
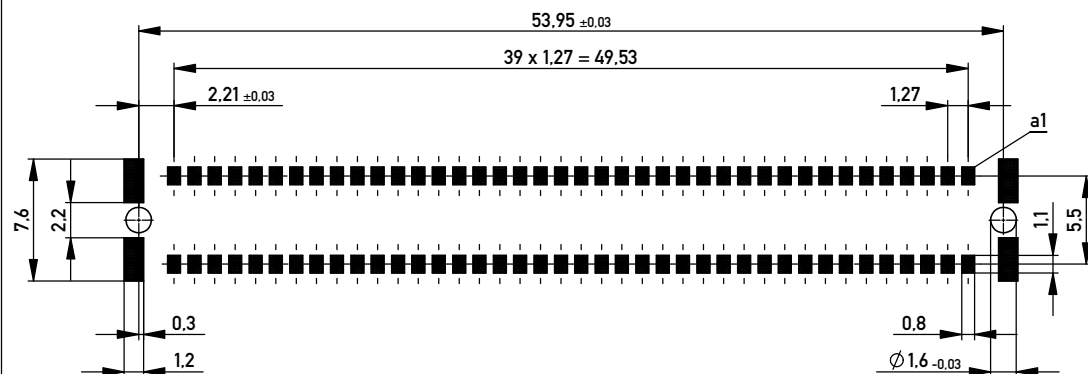
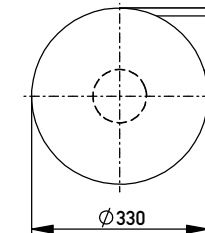




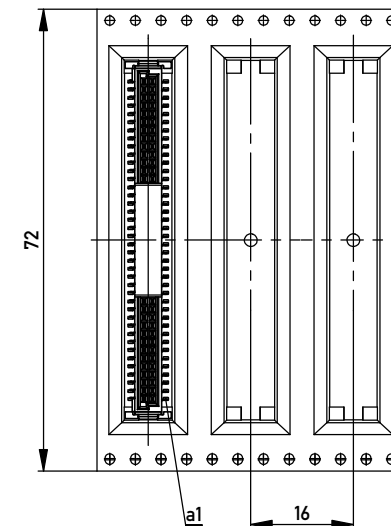
Leiterplatten-Layout Vorschlag für SMT
PCB-Layout Proposal for SMT



Verpackt im Gurt nach DIN IEC 60286-3
Tape on Reel Packaging according to DIN IEC 60286-3
Verpackungseinheit: 280 Stück
Packaging unit: 280 pcs



Abspulrichtung - Reel off Direction



Anforderungsstufe 1
Performance Level 1

Kontaktbereich vergoldet
Mating Area gold plating

Anschlussbereich verzinkt 4-6 µm
Terminal Area 4-6 µm tin plating

Koplanarität der Anschlüsse ≤ 0.1 mm
Coplanarity Area of Termination ≤ 0.1 mm

BA 7-03 - Standard Bauhöhe

type 7-03 - standard assembly height

Information:		Tolerances		Scale	3:1
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e		10.12.2013		Federl. SMC-B 80-SMD-BA7-03	
Index		Date		Female SMC-B 80-SMD-type7-03	
				154721	
				I	
				A3	
				Class	
				SMCB	

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